



Product Change Notification: MFOL-08RAHR410

Date:

12-Oct-2026

Product Category:

Gate Drivers and Motor Drivers

Notification Subject:

CCB 8590 Initial Notice: Qualification of 8200TNP as a new die attach material for selected CN2103, CN21814, CN2184, CN21064, MCP14LH2101, LF2101, MCP14LH2106, LF2106, MCP14H2103, LF2103, MCP14LH21904, LF21904, MCP14H2184, LF2184, LF21844, MCP14H2304, LF2304, MCP14LH21064, LF21064, MCP14H2104, LF2104, MCP14LH2181, LF2181, IXD2012, MCP14LH2190, LF2190, MCP14LH21814, LF21814 and MCP14L0227 device families available in 8L SOIC and 14L SOIC (.150in) packages at HTT assembly site.

Affected CPNs:

[MFOL-08RAHR410_Affected_CPN_10122026.pdf](#)

[MFOL-08RAHR410_Affected_CPN_10122026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 8200TNP as a new die attach material for selected CN2103, CN21814, CN2184, CN21064, MCP14LH2101, LF2101, MCP14LH2106, LF2106, MCP14H2103, LF2103, MCP14LH21904, LF21904, MCP14H2184, LF2184, LF21844, MCP14H2304, LF2304, MCP14LH21064, LF21064, MCP14H2104, LF2104, MCP14LH2181, LF2181, IXD2012, MCP14LH2190, LF2190, MCP14LH21814, LF21814 and MCP14L0227 device families available in 8L SOIC and 14L SOIC (.150in) packages at HTT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Tianshui Huatian Technology Co., Ltd (HTT)			Tianshui Huatian Technology Co., Ltd (HTT)			No
Wire Material	Cu	CuPd	CuPdAu	Cu	CuPd	CuPdAu	No
Die Attach Material	8200T (PFAS)			8200TNP (PFAS-Free)			Yes
Molding Compound Material	CEL-8240HF10GK			CEL-8240HF10GK			No
Lead-Frame Material	A194			A194			No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 8200TNP as a new die attach material at HTT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	March 2027				
Work Week	40	41	42	43	44		09	10	11	12	13
Initial PCN Issue Date			X								
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 12, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_MFOL-08RAHR410_Qualification Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.